

Test design :

Controllable DC/DC Buck

Converter

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Requirement:

- a. Focus on the controller - schematics and layout (ideally in Altium but could be any decent software that the candidate is most familiar with). Objective of layout demonstration is to show your considerations for ground returns, and noise-immune design concepts in general
- b. Select chip that can provide automatic cycle-by-cycle control of the duty cycle but at the same time take in control input from the microcontroller for target output current. Control input could be 0-5V voltage signal or digital comms (I2C / SPI, etc).
- c. Target SiC FET half-bridge modules as power devices (200A output current) - define switching frequency accordingly - such as <https://www.wolfspeed.com/cas300m12bm2>
- d. Note driver considerations for SiC FET module
- e. Note EMC considerations for SiC FET module

MATLAB Simulation

Using MATLAB code to calculate the values of the buck converter.

```
% Assume

fs= 100e3;

Vi=1000;

D=0.5;

R=2.5;

I_ripple=0.1;

V_ripple=0.05;


% Calculation

Vo=Vi*D

IL_avg=Vo/R

del_iL=I_ripple*IL_avg

del_vC=V_ripple*Vo

L=(Vo*(1-D))/(fs*del_iL)

C=(1-D)/(8*(fs^2)*L*(del_vC/Vo))

P=(Vo^2)/R
```

Thus, I can have the values of inductor, capacitor.

```
Vo =    500

IL_avg =    200

del_iL =     20

del_vC =     25

L =    1.2500e-04
```

C = 1.0000e-06

P = 100000

With those values, I use MATLAB Simulink to do the Buck converter with current program control.

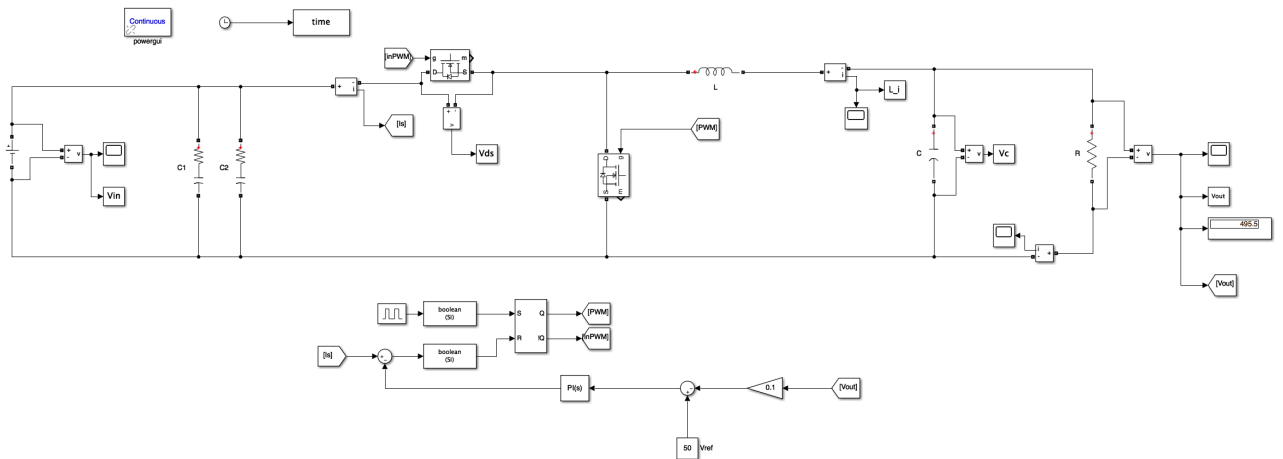


Figure 1 MATLAB Simulink model for Buck converter with current program control.

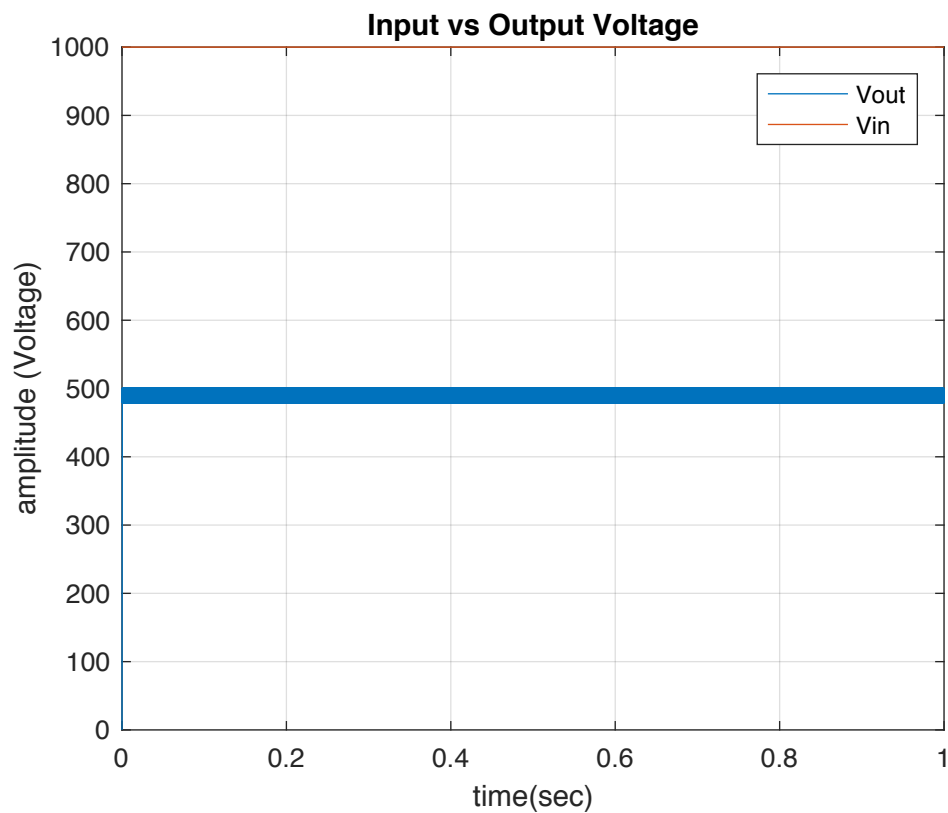


Figure 2 Input voltage and output voltage waveform.

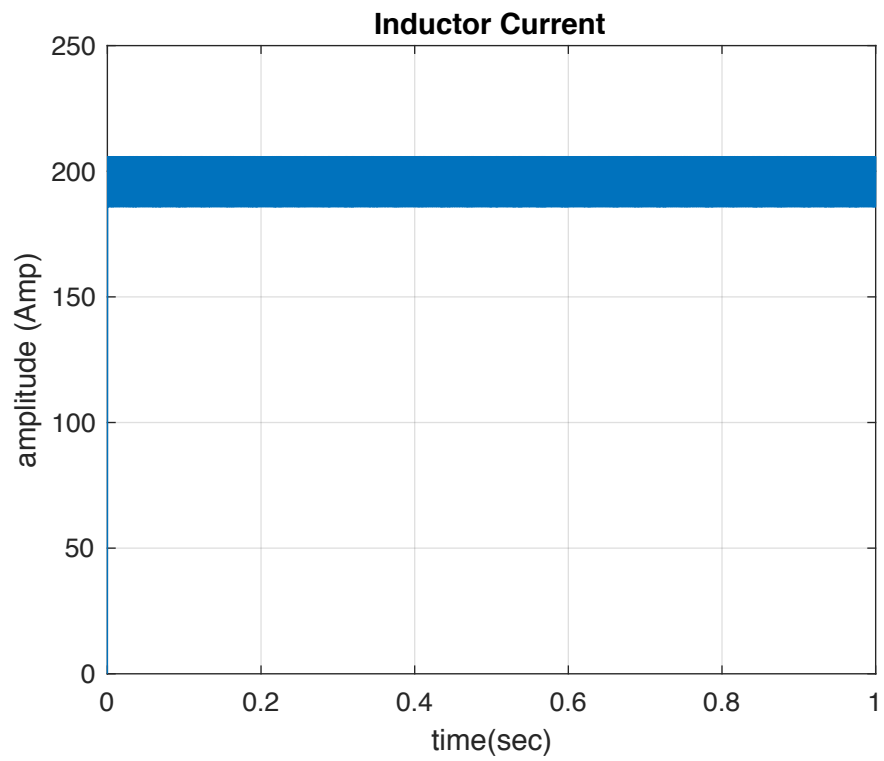


Figure 3 Inductor current waveform.

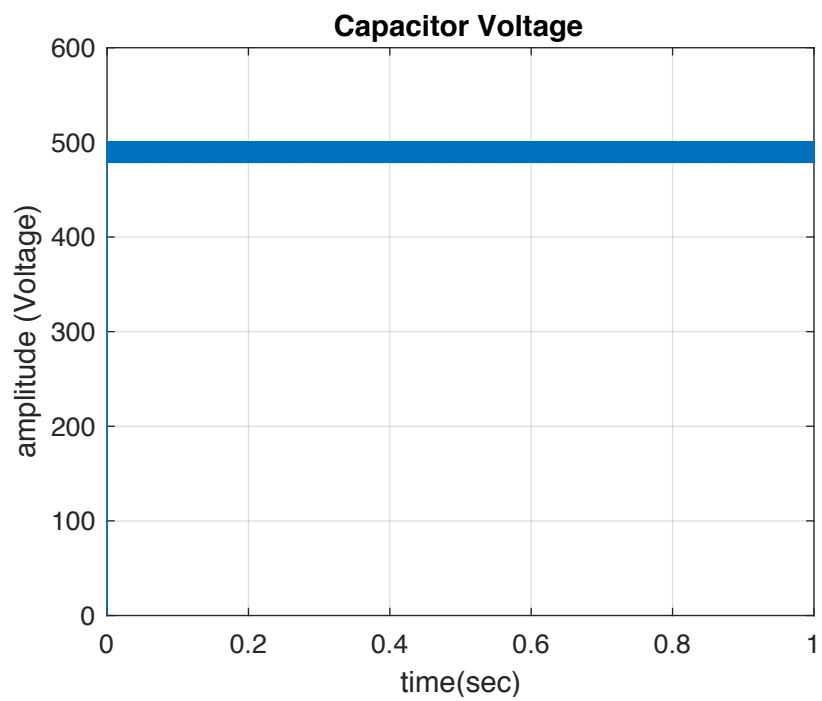


Figure 4 Capacitor voltage waveform.

Schematic Design

1 Converter Design

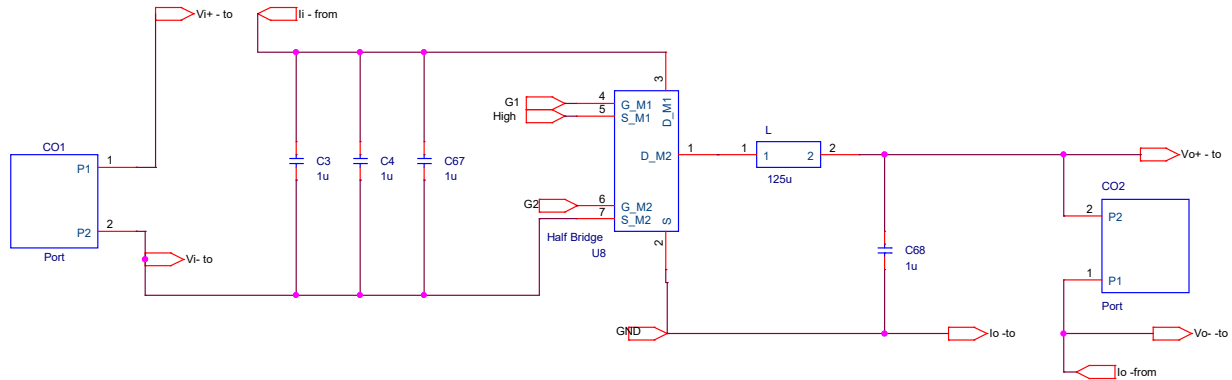


Figure 5 Schematic for proposed converter.

The design of this converter was followed in two discrete stages. The first was to develop the topologies in Simulink and test for the functionality and the stresses. Next, this result is used to determine which system needs to be made modular in order to reduce the stress and overall cost of the converter.

The converter used along with its auxiliary circuit is designed in OrCAD Capture and tested for its functionality. BOM of this designed converter is then generated. Footpads and Footprints are created in Allegro/PCB Editor for all the components. These footprints are then used in part placement. PCB stack up is then decided based on the maximum current each layer will be carrying.

The layout of the converter is then generated carefully while calculating and ensuring the trace width used on each layer. Once the layout is completed, Gerber files and NC drill files are generated in order to obtain a DFM report from the PCB manufacturer.

The input capacitor C_3 , C_4 , C_{67} are used as filters and to increase the bandwidth of the converter.

1.1 Isolated Gate Driver

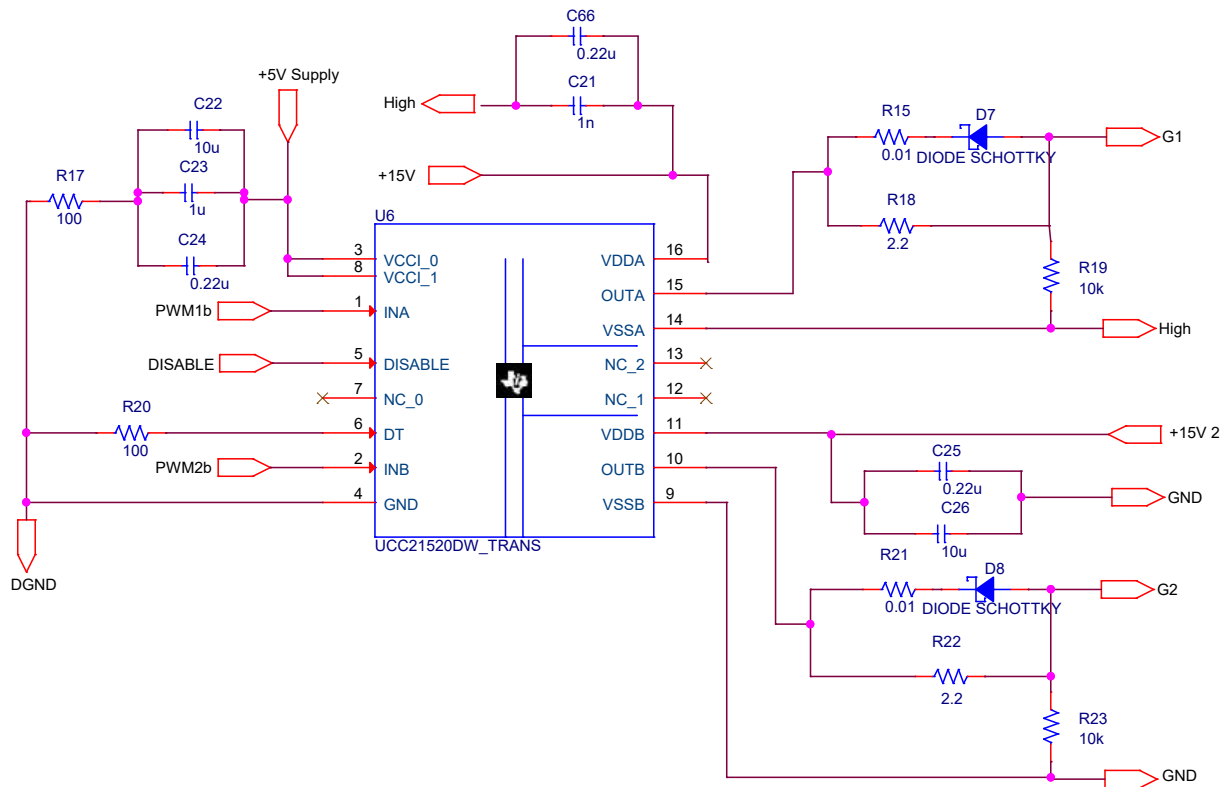


Figure 6 Schematic for isolated gate driver.

The UCC21520 is an isolated dual-channel gate driver with a 4-A source and 6-A sink peak current. The device is designed to drive power MOSFETs, IGBTs, and SiC MOSFETs up to 5 MHz with best-in-class propagation delay and pulse-width distortion. The input side is isolated from the two output drivers by a 5.7-kVRMS reinforced isolation barrier with a minimum of 100-V/ns common-mode transient immunity (CMTI). Internal functional isolation between the two secondary-side drivers allows a working voltage of up to 1500-V DC. A disable pin shuts down both outputs simultaneously when it is set high and allows normal operation when left floating or grounded. The device accepts V_{DD} supply voltages up to 25 V. A wide input V_{CCI} range from 3 V to 18 V makes the driver suitable for interfacing with both analog and digital controllers.

A bypass capacitor is connected to V_{CC1} supports the transient current needed for the primary logic and total current consumption i.e. a few mA. Thus, 50V MLCC > 100nF is recommended. A 1μF electrolytic capacitor is recommended to be connected in parallel to MLCC if the bias supply output is relatively long distance from the V_{CC1} pin.

DT Pin is used to introduce a dead time. Dead time can be introduced either through the microcontroller or by selecting a value of resistance. Here a value of resistance is selected with the help of simulation to introduce the necessary deadtime:

$$R_{DT} = 100\Omega$$

Resistor R_{in} and capacitor C_{in} are used to filter out the ringing introduced by non-ideal layout long PCB traces. Thus, their values are selected as follows

$$R_{in} = 0 \text{ to } 100\Omega$$

$$C_{in} = 10 \text{ to } 100\text{pF}$$

While selecting the bootstrap diode it is necessary to ensure high voltage and fast recovery diodes/Schottky diodes are chosen with low forward voltage drop and low junction capacitance in order to reduce losses.

Voltage rating of diode should be greater than the DC link voltage with a good margin. Resistor R_{BOOT} is used to reduce inrush current in D_{boot} and to limit the slew rate of V_{DDA} and V_{SSA} during each switching cycle. Thus, R_{BOOT} is selected in the range between 1Ω to 20Ω [Generally 2.2Ω should be fine]. V_{BDF} is the estimated diode forward voltage drop. It is essential to know the worst case peak current through the bootstrap diode in order to ensure that the gate drive is safe during this condition.

The external gate driver resistors R_{ON}/R_{OFF} is used to:

1. Limit ringing caused by parasitic capacitance/Inductance
2. Limit ringing caused by high voltage/current switching dv/dt , di/dt and body diode reverse recovery.
3. Peak sink and source current to optimize the switching loss
4. Reduce EMI

R_{OFF} is the resistance connected in series with the diode and is a very small value.

R_{19} and R_{23} are used to reduce the parasitic ringing.

1.2 Voltage Sensor

INPUT VOLTAGE SENSOR

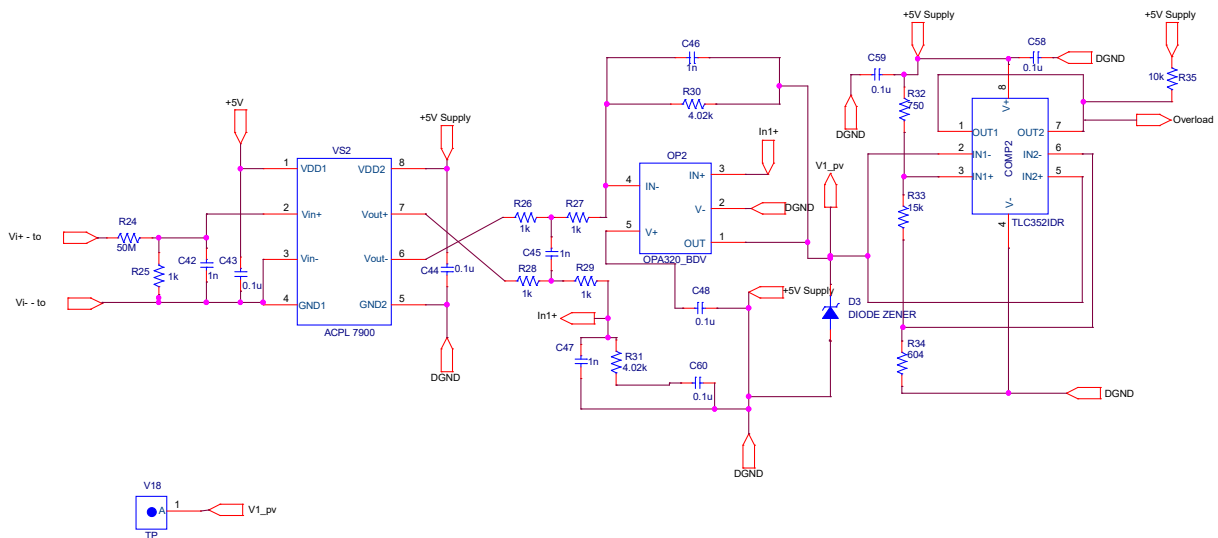


Figure 7 Schematic for voltage sensor.

The ACPL-7900 precision miniature isolation amplifiers are designed for voltage sensing in electronic power converter applications such as motor drives and renewable energy systems. In a typical converter implementation, current flows through an external resistor and the resulting analog voltage drop is sensed by the isolation amplifier. A differential output voltage that is proportional to the current is created on the other side of the optical isolation barrier. For general applications, ACPL-7900 ($\pm 3\%$ gain tolerance) are recommended. The voltage sensor operates from a single 5V supply and provides excellent linearity and dynamic performance of 60 dB SNR.

It has a 200 kHz bandwidth and 1.6 μs response time. Combined with superior optical coupling technology, the ACPL-7900 precision miniature isolation amplifiers implement sigma-delta analog-to-digital converter, chopper stabilized amplifiers, and a fully differential circuit topology to provide unequalled isolation-mode noise rejection, low offset, high gain accuracy and stability. This performance is delivered in a compact, auto-insertable DIP-8 package that meets worldwide

regulatory safety standards. These voltage sensors are used to sense the input and the output voltage in the Buck converter.

The maximum allowable input voltage of the voltage sensor is 200mV. Thus, a resistor divider circuit with $R_{24} = 50\text{M}$ and $R_{25} = 1\text{K}$ is used. The maximum input voltage is assumed to be 1000V. Using the resistor divider calculation:

$$V_{\text{out}} / V_{\text{in}} = R_2 / (R_1 + R_2)$$

$$V_{\text{out}} = 1000 * 1\text{k} / (50\text{M} + 1\text{k}) = 200\text{mV}$$

The gain of the sensor is 8.2(max). Thus, the maximum achievable output is $= 200\text{mV} \times 8.2 = 1.64\text{V}$. Thus, in the op-amp of the double ended to single ended circuit ahead of the output of the voltage sensor a gain of 2 is used to send a voltage of $2 \times 1.64 = 3.28\text{V}$ which is within the acceptable limits of the DSP input which is 3.3V.

Two resistors R_{26} and R_{27} of $1\text{K}\Omega$ each are used and a $4\text{K}\Omega$ resistor R_{30} is connected between the output and the input of the op-amp. This gives us the gain of the op-amp:

$$\text{Gain} = R_{30} / (R_{26} + R_{27}) = 4 / (1 + 1) = 2$$

Capacitor C_{45} is calculated using the formula

$$f = 2\pi RC. C = 100\text{K} / 2\pi \times (1 + 1) \text{K} = 0.8\text{nF} \approx 1\text{nF}.$$

1.3 Current Sensor

INPUT CURRENT SENSOR

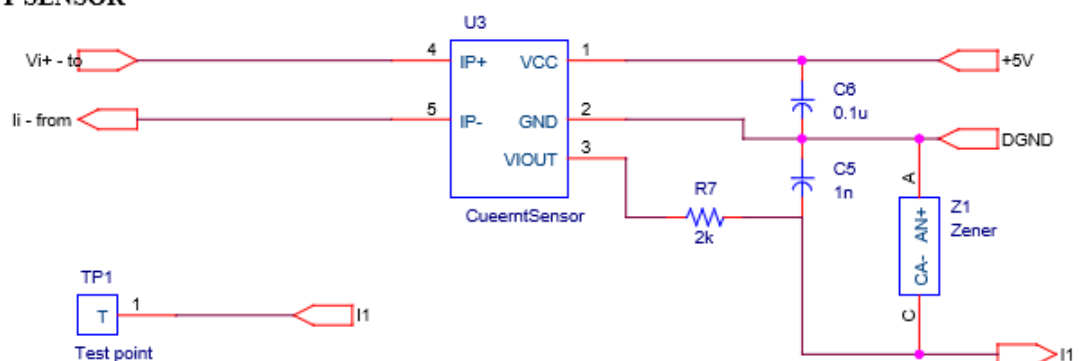


Figure 8 Schematic for current sensor.

The current sensor ACS770ECB-200U-PFF-T consists of a precision, low-offset linear Hall circuit with a copper conduction path located near the die. The sensor provides economical and precise solutions for AC or DC current sensing. Typical applications include motor control, load detection and management, power supply and DC-to-DC converter control, inverter control, and overcurrent fault detection. The current is sensed differentially in order to reject common-mode fields, improving accuracy in magnetically noisy environments. The inherent device accuracy is optimized through the close proximity of the magnetic field to the Hall transducer. A precise, proportional voltage is provided by the low-offset, chopper-stabilized BiCMOS Hall IC. The output of the device has a positive slope when an increasing current flows through the primary copper conduction path. This sensor is used to sense the input current and the output current.

1.4 Buffer

The SN74LV1T34 device is a low voltage CMOS gate logic that operates at a wider voltage range for industrial, portable, and telecom applications. The output level is referenced to the supply voltage and supports 1.8-V, 2.5-V, 3.3-V, and 5-V CMOS levels. The input has a lower threshold circuit to match 1.8 V input logic at $V_{CC} = 3.3\text{ V}$ and can be used in 1.8 V to 3.3 V level up translation. In addition, the 5 V tolerant input pins enable down translation (that is, 3.3 V to 2.5 V output at $V_{CC} = 2.5\text{ V}$). The wide V_{CC} range of 1.8 V to 5.5 V allows generation of desired output levels to connect to controllers or processors. The SN74LV1T34 device is designed with current drive capability of 8 mA to reduce line reflections, overshoot, and undershoot caused by high-drive outputs. The buffers are used to provide additional isolation between DSP and the isolated gate driver.

BUFFER 1

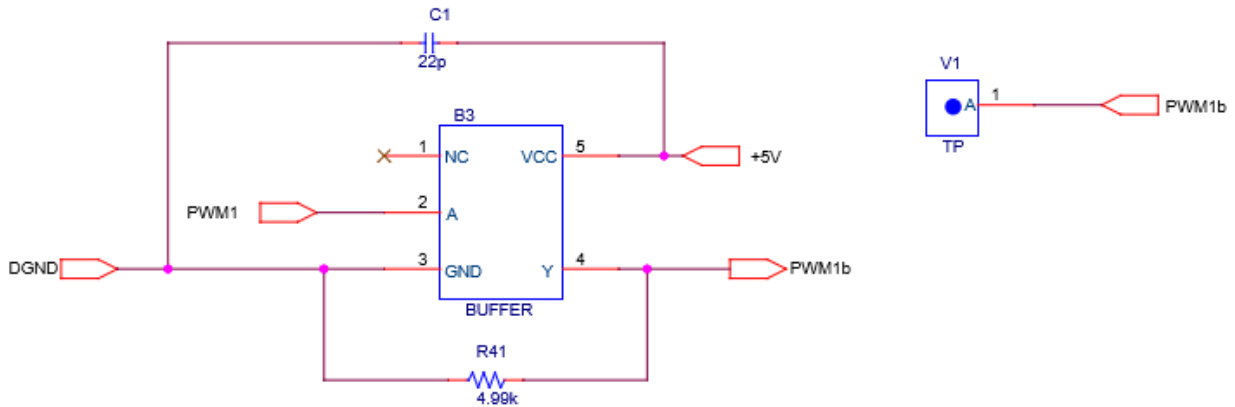


Figure 9 Schematic for buffer.

1.5 5V Regulator

An isolated DC-DC converter is selected whose input is 5V and provides a 5V fixed output.

5V REGULATOR 1

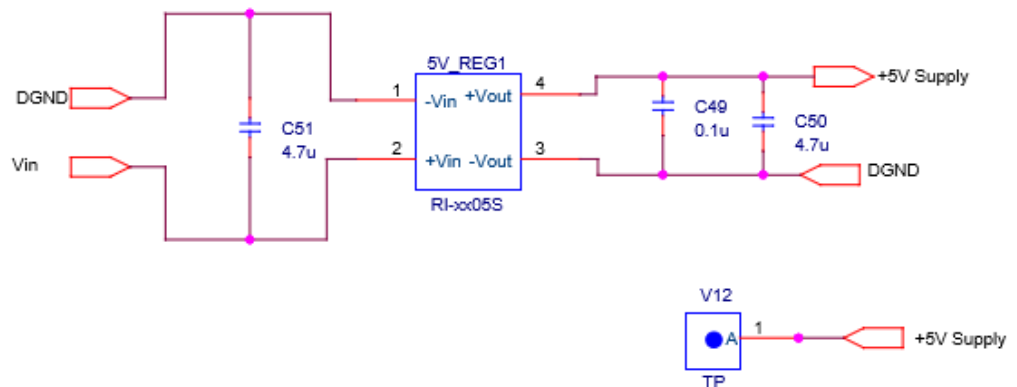


Figure 10 Schematic for 5V regulator.

1.6 15V Regulator

An isolated DC-DC converter is selected whose input is 5V and provides a 15V boosted output.

15V REGULATOR 1

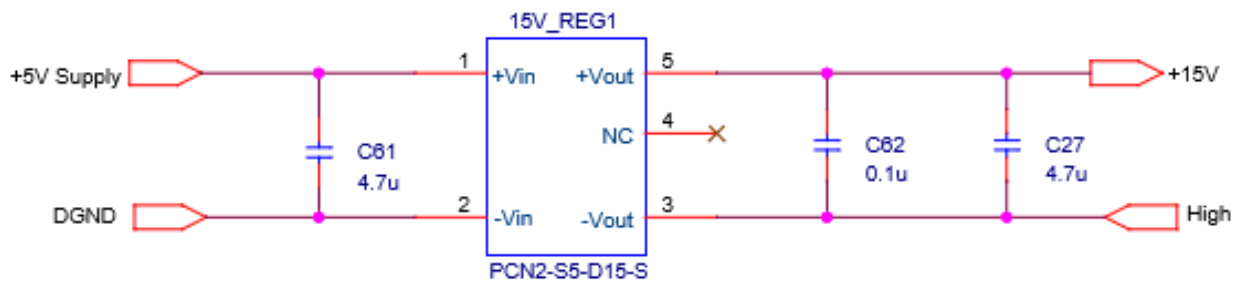


Figure 11 Schematic for 15V regulator.

PCB Layout

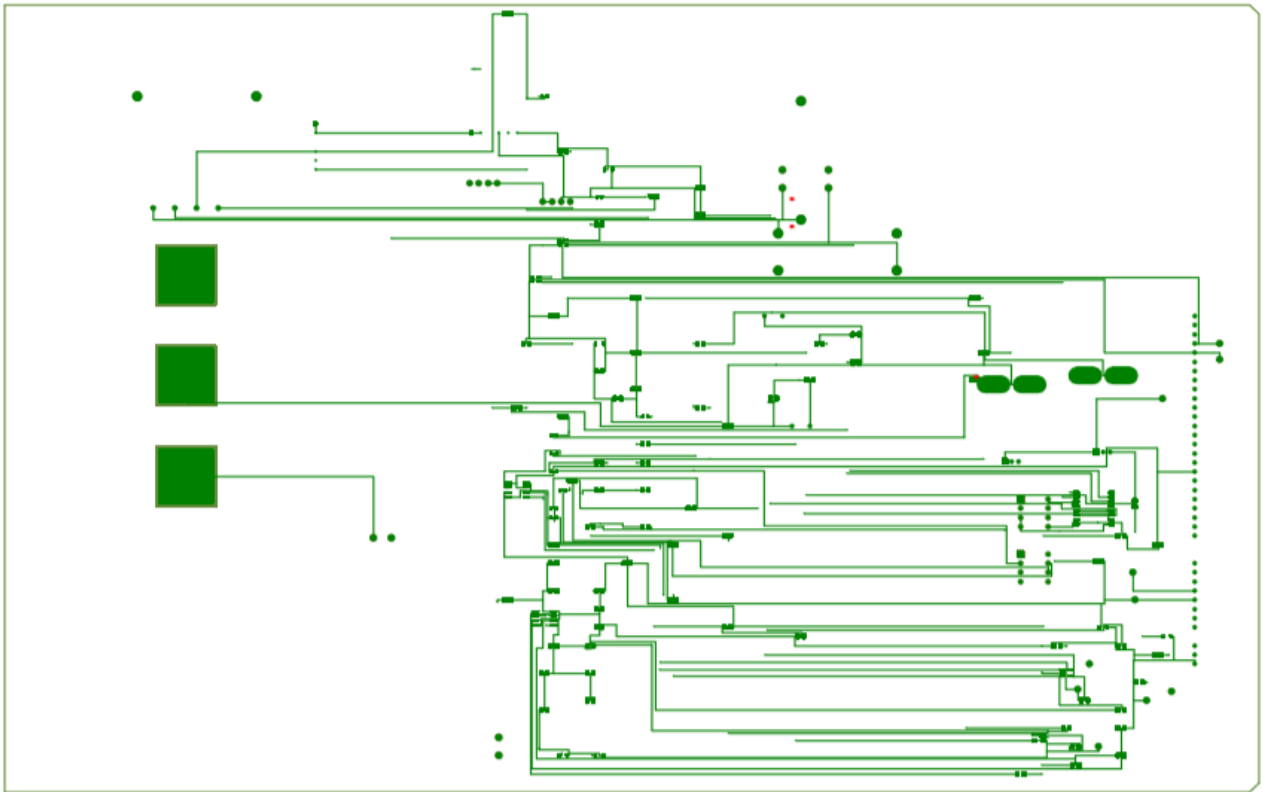


Figure 12 Top layer of the PCBA.

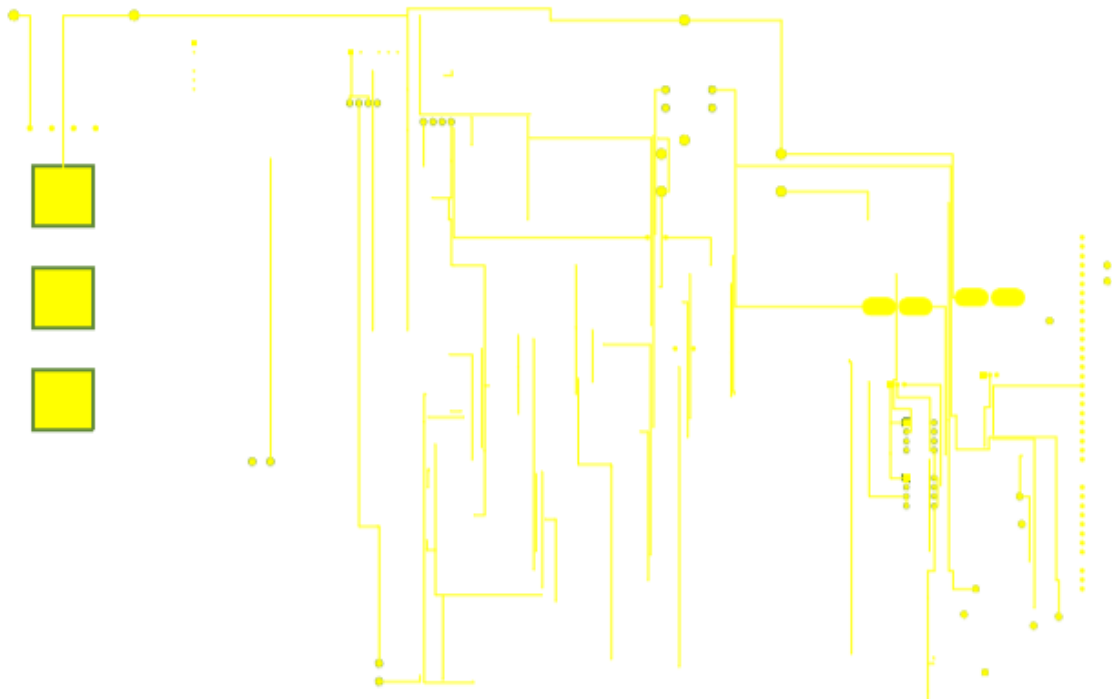


Figure 13 Bottom layer of the PCBA.

Future Work

1 EMC Consideration

To prevent the EMC in SiC MOSFET, we can use snubber circuit. A simple RC snubber uses a small resistor (R) in series with a small capacitor (C). This combination can be used to suppress the rapid rise in voltage across a thyristor, preventing the erroneous turn-on of the thyristor; it does this by limiting the rate of rise in voltage (dV/dt) across the thyristor to a value which will not trigger it. An appropriately-designed RC snubber can be used with either DC or AC loads. This sort of snubber is commonly used with inductive loads such as electric motors. The voltage across a capacitor cannot change instantaneously, so a decreasing transient current will flow through it for a small fraction of a second, allowing the voltage across the switch to increase more slowly when the switch is opened. Determination of voltage rating can be difficult owing to the nature of transient waveforms, and may be defined simply by the power rating of the snubber components and the application.

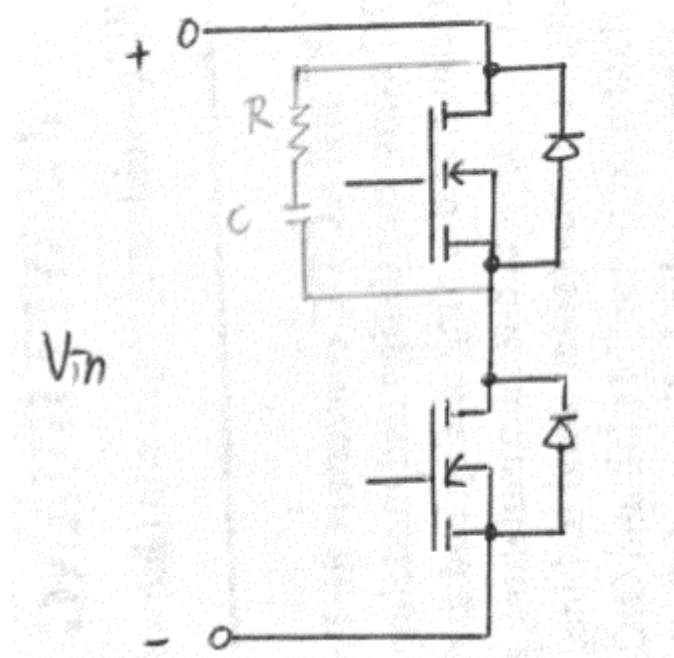


Figure 12 Proposed RC snubber circuit.

2 3 Level Switching Circuit

In order to reduce the ripple in inductor current and the current stress on the components, we can use the 3 level switching circuit. The advantage of using this circuit is that the switch loss will decrease.

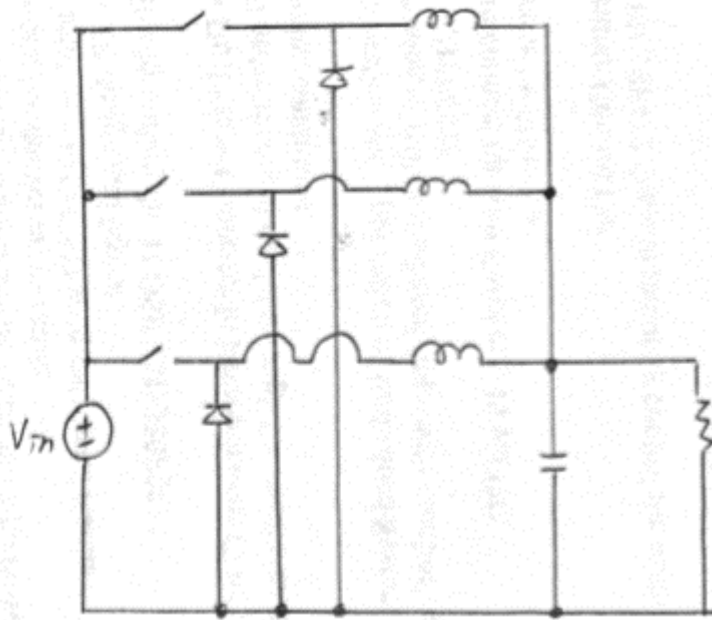


Figure 1 Proposed 3 level switching circuit.

DSP Coding

```
// Included Files
//
#include "F28x_Project.h"

//
// Defines
//
#define EPWM1_TIMER_TBPRD  588  // Period register
#define EPWM1_CMPA         294

#define EPWM2_TIMER_TBPRD  588  // Period register
#define EPWM2_CMPA         294

#define EPWM3_TIMER_TBPRD  588  // Period register
#define EPWM3_CMPA         294

#define EPWM4_TIMER_TBPRD  588  // Period register
#define EPWM4_CMPA         294

//
// Globals
//
Uint16 AdcaResult;
Uint16 AdcaResult_offsetAdjusted;
Uint16 AdcbResult;
Uint16 AdcbResult_offsetAdjusted;

//Uint16 ConversionCount;
Uint16 LoopCount;
Uint16 ConversionCount;
Uint16 Voltage1[10];
Uint16 Voltage2[10];
Uint16 Voltage3[10];
Uint16 Voltage4[10];

// Function Prototypes
//
void InitEPwm1Example(void);
void InitEPwm2Example(void);
void InitEPwm3Example(void);
void InitEPwm4Example(void);
void ConfigureADC(void);
void SetupADCSoftware(void);
interrupt void adc_isr(void);

//
// Main
//
void main(void)
{
//
// Step 1. Initialize System Control:
// PLL, WatchDog, enable Peripheral Clocks
// This example function is found in the F2837xD_SysCtrl.c file.
//
    InitSysCtrl();

//
// Step 2. Initialize GPIO:
```

```

// This example function is found in the F2837xD_Gpio.c file and
// illustrates how to set the GPIO to it's default state.
//
    InitGpio();

//
// enable PWM1, PWM2 and PWM3
//
    CpuSysRegs.PCLKCR2.bit.EPWM1=1;
    CpuSysRegs.PCLKCR2.bit.EPWM2=1;
    CpuSysRegs.PCLKCR2.bit.EPWM3=1;
    CpuSysRegs.PCLKCR2.bit.EPWM4=1;

//
// For this case just init GPIO pins for ePWM1, ePWM2, ePWM3, and ePWM4
// These functions are in the F2837xD_EPwm.c file
//
    InitEPwm1Gpio();
    InitEPwm2Gpio();
    InitEPwm3Gpio();
    InitEPwm4Gpio();

//
// Step 3. Clear all interrupts and initialize PIE vector table:
// Disable CPU interrupts
//
    DINT;

//
// Initialize the PIE control registers to their default state.
// The default state is all PIE interrupts disabled and flags
// are cleared.
// This function is found in the F2837xD_PieCtrl.c file.
//
    InitPieCtrl();

//
// Disable CPU interrupts and clear all CPU interrupt flags:
//
    IER = 0x0000;
    IFR = 0x0000;

//
// Initialize the PIE vector table with pointers to the shell Interrupt
// Service Routines (ISR).
// This will populate the entire table, even if the interrupt
// is not used in this example. This is useful for debug purposes.
// The shell ISR routines are found in F2837xD_DefaultIsr.c.
// This function is found in F2837xD_PieVect.c.
//
    InitPieVectTable();

// Interrupts that are used in this example are re-mapped to
// ISR functions found within this file.
    EALLOW; // This is needed to write to EALLOW protected register
    PieVectTable.ADCINT = &adc_isr;
    EDIS;    // This is needed to disable write to EALLOW protected registers

// Step 4. Initialize all the Device Peripherals:
// This function is found in DSP2833x_InitPeripherals.c
// InitPeripherals(); // Not required for this example
    InitAdc(); // For this example, init the ADC

```

```

    EALLOW;
    CpuSysRegs.PCLKCR0.bit.TBCLKSYNC = 0;
    EDIS;

// Step 5. User specific code,

// Enable ADCINT in PIE
    PieCtrlRegs.PIEIER1.bit.INTx6 = 1;
    IER |= M_INT1; // Enable CPU Interrupt 1
    EINT;           // Enable Global interrupt INTM
    ERTM;           // Enable Global realtime interrupt DBGM

    LoopCount = 0;
    ConversionCount = 0;
    ConfigureADC();

// Wait for ADC interrupt
    for(;;)
    {
        LoopCount++;
    }

}

//
// InitEPwm1Example - Initialize EPWM1 configuration
//
void InitEPwm1Example()
{
    //
    // Setup TBCLK
    //
    EPwm1Regs.TBPRD = EPWM1_TIMER_TBPRD; // Set timer period
    EPwm1Regs.TBPHS.bit.TBPHS = 0x0000; // Phase is 0
    EPwm1Regs.TBCTR = 0x0000; // Clear counter

    //
    // Set Compare values
    //
    EPwm1Regs.CMPA.bit.CMPA = EPWM1_CMPA; // Set compare A value

    //
    // Setup counter mode
    //
    EPwm1Regs.TBCTL.bit.CTRMODE = TB_COUNT_UPDOWN; // Count up and down
    EPwm1Regs.TBCTL.bit.PHSEN = TB_DISABLE; // Disable phase loading
    EPwm1Regs.TBCTL.bit.PRDL = TB_SHADOW;
    EPwm1Regs.TBCTL.bit.SYNCSEL = TB_CTR_ZERO; // Sync down-stream module
    EPwm1Regs.TBCTL.bit.HSPCLKDIV = TB_DIV1; // Clock ratio to SYSCLKOUT
    EPwm1Regs.TBCTL.bit.CLKDIV = TB_DIV1;

    //
    // Setup shadowing
    //
    EPwm1Regs.CMPCTL.bit.SHDWAMODE = CC_SHADOW;
    EPwm1Regs.CMPCTL.bit.SHDWBMODE = CC_SHADOW;
    EPwm1Regs.CMPCTL.bit.LOADAMODE = CC_CTR_ZERO; // Load on Zero
    EPwm1Regs.CMPCTL.bit.LOADBMODE = CC_CTR_ZERO;

    //

```

```

// Set actions
//
EPwm1Regs.AQCTLA.bit.CAU = AQ_SET;           // Set PWM1A on event A, up
                                              // count
EPwm1Regs.AQCTLA.bit.CAD = AQ_CLEAR;         // Clear PWM1A on event A,
                                              // down count

// Dead Band
EPwm1Regs.DBCTL.bit.OUT_MODE = DB_FULL_ENABLE; // enable Dead-band module
EPwm1Regs.DBCTL.bit.POLSEL = DB_ACTV_HIC;      // Active Hi complementary
EPwm1Regs.DBFED.bit.DBFED = 50;                // FED = 150 ns
EPwm1Regs.DBRED.bit.DBRED = 50;                // RED = 150 ns
}

//
// InitEPwm2Example - Initialize EPWM2 configuration
//
void InitEPwm2Example()
{
    //
    // Setup TBCLK
    //
    EPwm2Regs.TBPRD = EPWM2_TIMER_TBPRD;       // Set timer period
    EPwm2Regs.TBPHS.bit.TBPHS = 0x0000;        // Phase is 0
    EPwm2Regs.TBCTR = 0x0000;                  // Clear counter

    //
    // Set Compare values
    //
    EPwm2Regs.CMPA.bit.CMPA = EPWM2_CMPA;      // Set compare A value

    //
    // Setup counter mode
    //
    EPwm2Regs.TBCTL.bit.CTRMODE = TB_COUNT_UPDOWN; // Count up and down
    EPwm2Regs.TBCTL.bit.PHSEN = TB_ENABLE;         // Enable phase loading
    EPwm2Regs.TBCTL.bit.PRDLN = TB_SHADOW;
    EPwm2Regs.TBCTL.bit.SYNCSEL = TB_SYNC_IN;      // sync flow-through
    EPwm2Regs.TBCTL.bit.HSPCLKDIV = TB_DIV1;       // Clock ratio to SYSCLKOUT
    EPwm2Regs.TBCTL.bit.CLKDIV = TB_DIV1;

    //
    // Setup shadowing
    //
    EPwm2Regs.CMPCTL.bit.SHDWAMODE = CC_SHADOW;
    EPwm2Regs.CMPCTL.bit.SHDWBMODE = CC_SHADOW;
    EPwm2Regs.CMPCTL.bit.LOADAMODE = CC_CTR_ZERO; // Load on Zero
    EPwm2Regs.CMPCTL.bit.LOADBMODE = CC_CTR_ZERO;

    //
    // Set actions
    //
    EPwm2Regs.AQCTLA.bit.CAU = AQ_CLEAR;         // Clear PWM2A on event A, up
                                              // count
    EPwm2Regs.AQCTLA.bit.CAD = AQ_SET;           // Set PWM2A on event B, down
                                              // count

    // Dead Band
    EPwm2Regs.DBCTL.bit.OUT_MODE = DB_FULL_ENABLE; // enable Dead-band module
    EPwm2Regs.DBCTL.bit.POLSEL = DB_ACTV_HIC;      // Active Hi complementary
    EPwm2Regs.DBFED.bit.DBFED = 50;                // FED = 150 ns
    EPwm2Regs.DBRED.bit.DBRED = 50;                // RED = 150 ns
}

//

```

```

// InitEPwm3Example - Initialize EPWM3 configuration
//
void InitEPwm3Example(void)
{
    //
    // Setup TBCLK
    //
    EPwm3Regs.TBPRD = EPWM3_TIMER_TBPRD;           // Set timer period
    EPwm3Regs.TBPHS.bit.TBPHS = 0x0000;           // Phase is 0
    EPwm3Regs.TBCTR = 0x0000;                       // Clear counter

    //
    // Set Compare values
    //
    EPwm3Regs.CMPA.bit.CMPA = EPWM3_CMPA;          // Set compare A value

    //
    // Setup counter mode
    //
    EPwm3Regs.TBCTL.bit.CTRMODE = TB_COUNT_UPDOWN; // Count up and down
    EPwm3Regs.TBCTL.bit.PHSEN = TB_ENABLE;          // Enable phase loading
    EPwm3Regs.TBCTL.bit.PRDL = TB_SHADOW;
    EPwm3Regs.TBCTL.bit.SYNCSEL = TB_SYNC_IN;        // sync flow-through
    EPwm3Regs.TBCTL.bit.HSPCLKDIV = TB_DIV1;         // Clock ratio to
SYSCLKOUT
    EPwm3Regs.TBCTL.bit.CLKDIV = TB_DIV1;

    //
    // Setup shadowing
    //
    EPwm3Regs.CMPCTL.bit.SHDWAMODE = CC_SHADOW;
    EPwm3Regs.CMPCTL.bit.SHDWBMODE = CC_SHADOW;
    EPwm3Regs.CMPCTL.bit.LOADAMODE = CC_CTR_ZERO;    // Load on Zero
    EPwm3Regs.CMPCTL.bit.LOADBMODE = CC_CTR_ZERO;

    //
    // Set actions
    //
    EPwm3Regs.AQCTLA.bit.CAU = AQ_SET;               // Set PWM3A on event A, up
                                                    // count
    EPwm3Regs.AQCTLA.bit.CAD = AQ_CLEAR;             // Clear PWM3A on event B,
down
                                                    // count

    // Dead Band
    EPwm3Regs.DBCTL.bit.OUT_MODE = DB_FULL_ENABLE;   // enable Dead-band
module
    EPwm3Regs.DBCTL.bit.POLSEL = DB_ACTV_HIC;        // Active Hi
complementary
    EPwm3Regs.DBFED.bit.DBFED = 50;                 // FED = 150 ns
    EPwm3Regs.DBRED.bit.DBRED = 50;                 // RED = 150 ns

}

//
// InitEPwm4Example - Initialize EPWM4 configuration
//
void InitEPwm4Example(void)
{
    //
    // Setup TBCLK
    //
    EPwm4Regs.TBPRD = EPWM4_TIMER_TBPRD;           // Set timer period
    EPwm4Regs.TBPHS.bit.TBPHS = 0x0000;           // Phase is 0
    EPwm4Regs.TBCTR = 0x0000;                       // Clear counter

```

```

//
// Set Compare values
//
EPwm4Regs.CMPA.bit.CMPA = EPWM4_CMPA;    // Set compare A value

//
// Setup counter mode
//
EPwm4Regs.TBCTL.bit.CTRMODE = TB_COUNT_UPDOWN; // Count up and down
EPwm4Regs.TBCTL.bit.PHSEN = TB_ENABLE;        // Enable phase loading
EPwm4Regs.TBCTL.bit.PRDL = TB_SHADOW;
EPwm4Regs.TBCTL.bit.SYNCSEL = TB_SYNC_IN;     // sync flow-through
EPwm4Regs.TBCTL.bit.HSPCLKDIV = TB_DIV1;      // Clock ratio to
SYSCLKOUT
EPwm4Regs.TBCTL.bit.CLKDIV = TB_DIV1;

//
// Setup shadowing
//
EPwm4Regs.CMPCTL.bit.SHDWAMODE = CC_SHADOW;
EPwm4Regs.CMPCTL.bit.SHDWBMODE = CC_SHADOW;
EPwm4Regs.CMPCTL.bit.LOADAMODE = CC_CTR_ZERO; // Load on Zero
EPwm4Regs.CMPCTL.bit.LOADBMODE = CC_CTR_ZERO;

//
// Set actions
//
EPwm4Regs.AQCTLA.bit.CAU = AQ_CLEAR;        // Clear PWM4A on event A, up
// count
EPwm4Regs.AQCTLA.bit.CAD = AQ_SET;          // Set PWM4A on event B, down
// count

// Dead Band
EPwm4Regs.DBCTL.bit.OUT_MODE = DB_FULL_ENABLE; // enable Dead-band
module
    EPwm4Regs.DBCTL.bit.POLSEL = DB_ACTV_HIC;    // Active Hi
complementary
    EPwm4Regs.DBFED.bit.DBFED = 50;             // FED = 150ns
    EPwm4Regs.DBRED.bit.DBRED = 50;             // RED = 150ns
}

void ConfigureADC(void)
{
    EALLOW;

    //
    //write configurations
    //
    AdcaRegs.ADCCTL2.bit.PRESCALE = 6; //set ADCCLK divider to /4
    AdcbRegs.ADCCTL2.bit.PRESCALE = 6; //set ADCCLK divider to /4
    AdcSetMode(ADC_ADCA, ADC_RESOLUTION_12BIT, ADC_SIGNALMODE_SINGLE);
    AdcSetMode(ADC_ADCB, ADC_RESOLUTION_12BIT, ADC_SIGNALMODE_SINGLE);

    //
    //Set pulse positions to late
    //
    AdcaRegs.ADCCTL1.bit.INTPULSEPOS = 1;
    AdcbRegs.ADCCTL1.bit.INTPULSEPOS = 1;

    //
    //power up the ADCs
    //
    AdcaRegs.ADCCTL1.bit.ADCPWDNZ = 1;

```

```

    AdcbRegs.ADCCTL1.bit.ADCPDNZ = 1;

    //
    //delay for 1ms to allow ADC time to power up
    //
    DELAY_US(1000);

    EDIS;
}

//
// SetupADCSoftware - Configure ADC SOC and acquisition window
//
void SetupADCSoftware(void)
{
    Uint16 acqps;

    //
    //determine minimum acquisition window (in SYSCLKS) based on resolution
    //
    if(ADC_RESOLUTION_12BIT == AdcaRegs.ADCCTL2.bit.RESOLUTION)
    {
        acqps = 14; //75ns
    }
    else //resolution is 16-bit
    {
        acqps = 63; //320ns
    }

    //
    //Select the channels to convert and end of conversion flag
    //ADCA
    //
    EALLOW;
    AdcaRegs.ADCSOC0CTL.bit.CHSEL = 0; //SOC0 will convert pin A0
    AdcaRegs.ADCSOC0CTL.bit.ACQPS = acqps; //sample window is 100 SYSCLK cycles
    AdcaRegs.ADCSOC1CTL.bit.CHSEL = 0; //SOC1 will convert pin A0
    AdcaRegs.ADCSOC1CTL.bit.ACQPS = acqps; //sample window is 100 SYSCLK cycles
    AdcaRegs.ADCINTSEL1N2.bit.INT1SEL = 1; //end of SOC1 will set INT1 flag
    AdcaRegs.ADCINTSEL1N2.bit.INT1E = 1; //enable INT1 flag
    AdcaRegs.ADCINTFLGCLR.bit.ADCINT1 = 1; //make sure INT1 flag is cleared
    //
    //ADCB
    //
    AdcbRegs.ADCSOC0CTL.bit.CHSEL = 0; //SOC0 will convert pin B0
    AdcbRegs.ADCSOC0CTL.bit.ACQPS = acqps; //sample window is 100 SYSCLK cycles
    AdcbRegs.ADCSOC1CTL.bit.CHSEL = 0; //SOC1 will convert pin B0
    AdcbRegs.ADCSOC1CTL.bit.ACQPS = acqps; //sample window is 100 SYSCLK cycles
    AdcbRegs.ADCINTSEL1N2.bit.INT1SEL = 1; //end of SOC1 will set INT1 flag
    AdcbRegs.ADCINTSEL1N2.bit.INT1E = 1; //enable INT1 flag
    AdcbRegs.ADCINTFLGCLR.bit.ADCINT1 = 1; //make sure INT1 flag is cleared
    EDIS;
}

interrupt void adc_isr(void)
{
    Voltage1[ConversionCount] = AdcRegs.ADCRESULT0 >>4;
    Voltage2[ConversionCount] = AdcRegs.ADCRESULT1 >>4;
    Voltage3[ConversionCount] = AdcRegs.ADCRESULT2 >>4;
    Voltage4[ConversionCount] = AdcRegs.ADCRESULT3 >>4;
    Voltage5[ConversionCount] = AdcRegs.ADCRESULT4 >>4;
    Voltage6[ConversionCount] = AdcRegs.ADCRESULT5 >>4;
    Voltage7[ConversionCount] = AdcRegs.ADCRESULT6 >>4;
}

```

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Voltage8[ConversionCount] = AdcRegs.ADCRESULT7 >>4;
Voltage9[ConversionCount] = AdcRegs.ADCRESULT8 >>4;

// If 40 conversions have been logged, start over
if(ConversionCount == 9)
{
    ConversionCount = 0;
}
else ConversionCount++;

// Reinitialize for next ADC sequence
AdcRegs.ADCTRL2.bit.RST_SEQ1 = 1;           // Reset SEQ1
AdcRegs.ADCST.bit.INT_SEQ1_CLR = 1;         // Clear INT SEQ1 bit
AdcRegs.ADCTRL2.bit.RST_SEQ2 = 1;           // Reset SEQ1
    AdcRegs.ADCST.bit.INT_SEQ2_CLR = 1;       // Clear INT SEQ1 bit
PieCtrlRegs.PIEACK.all = PIEACK_GROUP1;     // Acknowledge interrupt to PIE

return;
}

```


BOM

Index	Quantity	Manufacturer Part Number	Description
1	3	OSTYC022150	TERMINAL BLOCK 5.08MM 2POS PCB
2	4	SV12AC105KAR	CAP CER 1UF 1KV X7R RADIAL
3	1	CAS300M12BM2	MOSFET 2N-CH 1200V 404A MODULE
4	2	ACS770ECB-200U-PFF-T	SENSOR CURRENT HALL 200A DC
5	2	RN73C2A2K0BTDF	RES SMD 2K OHM 0.1% 1/10W 0805
6	9	C0805C102K5RACTU	CAP CER 1000PF 50V X7R 0805
7	18	GCM21BR72A104KA37L	CAP CER 0.1UF 100V X7R 0805
8	6	MM3Z3V3B	DIODE ZENER 3.3V 200MW SOD323F
9	2	ACPL-790B-300E	IC OPAMP ISOLATION 200KHZ 8DIPGW
10	2	OPA320AIDBVR	C OPAMP GP 20MHZ RRO SOT23-5
11	2	TLC352IDR	IC DIFF VOLT COMP DUAL 8-SOIC
12	1	RH73H2A50MKTN	RES SMD 50M OHM 10% 1/8W 0805
13	10	TNPW08051K00BEEA	RES 1K OHM 0.1% 1/5W 0805
14	4	ERA-6AEB4021V	RES SMD 4.02K OHM 0.1% 1/8W 0805
15	2	RR1220P-751-D	RES SMD 750 OHM 0.5% 1/10W 0805
16	2	ERA-6AEB153V	RES SMD 15K OHM 0.1% 1/8W 0805
17	2	RR1220P-103-D	RES SMD 10K OHM 0.5% 1/10W 0805
18	2	RNCP0805FTD604R	RES 604 OHM 1% 1/4W 0805
19	1	HVC0805T2504JET	RES SMD 2.5M OHM 5% 1/8W 0805
20	2	PCN2-S5-D15-S	DC DC CONVERTER +/-15V 2W
21	8	GRM21BR61H475KE51L	CAP CER 4.7UF 50V X5R 0805
22	2	RI-xx05S	DC DC CONVERTER 5V 2W
23	2	SN74LV1T34DCKR	IC BUF NON-INVERT 5.5V SC70-5
24	2	RG2012P-4991-B-T5	RES SMD 4.99K OHM 0.1% 1/8W 0805
25	2	C0805C220J5GACTU	CAP CER 22PF 50V C0G/NP0 0805
26	1	UCC21520DWR	DGTL ISO 5.7KV GATE DRVR 16SOIC
27	2	RL1220T-R010-J	RES 0.01 OHM 5% 1/4W 0805
28	2	RCS08052R20JNEA	RES SMD 2.2 OHM 5% 0.4W 0805
29	2	TNPW080510K0BEEA	RES 10K OHM 0.1% 1/5W 0805
30	2	ERA-6AEB101V	RES SMD 100 OHM 0.1% 1/8W 0805
31	2	GRM21BR61E106KA73L	CAP CER 10UF 25V X5R 0805
32	3	UMK212B7224KG-T	CAP CER 0.22UF 50V X7R 0805
33	1	CC0805KKX7R8BB105	CAP CER 1UF 25V X7R 0805
34	1	61300311121	CONN HEADER 3 POS 2.54
35	1	61302511121	CONN HEADER 25 POS 2.54
36	1	61300811121	CONN HEADER 8 POS 2.54